

Starting up a new Sales Office in France for Circuit Testing Connector Business

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■ Summary

Yokowo is taking aim at a major worldwide market for semi-conductors to expand its Circuit Testing Connector business in Europe. Yokowo established a sales office in France to handle the semi-conductor test equipment market.

■ Background & Situation of Market

Yokowo regularly makes Mid-term Plans to identify targets for success in the future. This plan helps us to focus on and remain up to date on new Circuit Testing Connector business opportunities abroad. In order to ensure business opportunities related to IC Sockets, we decided to establish an office in France.

In 2004, the European Market accounted for approximately 20% of worldwide semi-conductor demand. By projection, we can forecast an increase in demand of 15%. The development of BGA/CSP packaged IC(※) which feature small and advance function test sockets are expected to increase production at manufacturing sites in the future. Thus, business can be expected to expand in the future.

■ Our future plan

Prior to opening the new office, Yokowo dealt with European business directly from its headquarters in Japan. However, by creating a local office in France, we feel that we will be better able to serve our customer's needs. Our objective is focused on future expansion of major semi-conductor manufacturing. The new office is located in Paris (France) and will be operational from May, 2005.

Major European semi-conductor manufacturing facilities also contain "Product Development Centers" and "Pilot Function Plants" which have a big influence in the worldwide market. Therefore, obtaining Maker Layout decisions in Europe is an important factor for business expansion worldwide.

In such a market environment, the new Yokowo office plans to have engineering support for the new BGA / QFN and other testing sockets for newly developed semi-conductor devices. We also plan to reinforce the liaison with the Yokowo headquarters' Technical Division. In order to propose solutions for our customers, suitable for their testing needs, Yokowo will speed up development and strive for the establishment of a solid business foundation.

With this Action Plan, we are aiming for a European Circuit Testing Connector annual turnover of 1.2 billion Japanese Yen by 2008.

《 New Office Profile 》

Company Name : Yokowo (France) S.A.S.
Incorporation : March 24th, 2005
Representative : Philippe Huysveld
Capital : 400,000 Euros [Funding: Yokowo Co, Ltd 100%]
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New Office 「Yokowo (France) S.A.S」 External View

※ QFN : Quad Flat Non-leaded Package

One type of IC chip packaging
High density surface PKG type

BGA : Ball Grid Array

BGA is another type of IC Packaging with more pins than QFN. The new Solder Ball technology which features round solder material is used on the socket. The solder ball arrays on the bottom of IC package. In contrary of the QFN, the bottom of IC PKG can make contact with the PCB and many pins can be installed on it.

CSP : Chip Size Package or Chip Scale Package(Name Generically)

For example:
BGA (Ball Grid Array) type
LGA (Land Grid Array) type
SON (Small Outline Nonleaded package) type

Enquiries about this new release to:

Connector Company
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